

119TH CONGRESS
1ST SESSION

H. R. 5332

To direct the Comptroller General of the United States to conduct a technology assessment focused on liquid-cooling systems for artificial-intelligence compute clusters and high-performance computing facilities, require the development of Federal Government-wide best-practice guidance for Federal agencies, and for other purposes.

IN THE HOUSE OF REPRESENTATIVES

SEPTEMBER 11, 2025

Mr. OBERNOLTE (for himself and Mr. GOTTHEIMER) introduced the following bill; which was referred to the Committee on Energy and Commerce, and in addition to the Committee on Science, Space, and Technology, for a period to be subsequently determined by the Speaker, in each case for consideration of such provisions as fall within the jurisdiction of the committee concerned

A BILL

To direct the Comptroller General of the United States to conduct a technology assessment focused on liquid-cooling systems for artificial-intelligence compute clusters and high-performance computing facilities, require the development of Federal Government-wide best-practice guidance for Federal agencies, and for other purposes.

1 *Be it enacted by the Senate and House of Representa-*
2 *tives of the United States of America in Congress assembled,*

1 **SECTION 1. SHORT TITLE AND PURPOSE.**

2 This Act may be cited as the “Liquid Cooling for AI
3 Act of 2025”.

4 **SEC. 2. FINDINGS.**

5 Congress finds the following:

6 (1) The 2024 United States Data Center En-
7 ergy Usage Report published by Lawrence Berkeley
8 National Laboratory indicates that data centers ac-
9 counted for 4.4 percent of total United States elec-
10 tricity consumption in 2023, up from 1.9 percent in
11 2018. The report further projects that data centers
12 could represent between 6.7 percent and 12.8 per-
13 cent of total electricity consumption by 2028, due to
14 the rapid growth of AI, cloud computing, and other
15 digital technologies.

16 (2) Traditional air-cooled systems are reaching
17 limits to effectively remove heat from AI chips and
18 hardware, and liquid cooling enhanced thermal per-
19 formance is increasingly becoming a necessity for
20 high-density AI servers and data centers due to the
21 growing power consumption and heat generation of
22 AI workloads.

23 (3) Liquid-cooling technologies, including di-
24 rect-to-chip (DTC) liquid cooling and single-phase or
25 two-phase immersion cooling, can improve thermal
26 performance, enable higher densities, and reduce

1 cooling system load when properly engineered and
2 maintained.

3 (4) Effective liquid-cooling deployments require
4 interoperable components and engineered sub-
5 systems, including coolant distribution units, sec-
6 ondary loops, manifolds, hoses, quick-disconnects,
7 valves, pumps, filters, leak detection and contain-
8 ment, corrosion control, and appropriate instrumen-
9 tation and controls.

10 (5) Interfaces for heat-reuse are integral to liq-
11 uid systems and can reduce thermal load on heat-re-
12 jection equipment by transferring heat through plate
13 heat exchangers or other devices to beneficial sec-
14 ondary uses where technically appropriate.

15 (6) Federal agencies, including the Department
16 of Energy, are considering the deployment of AI sys-
17 tems across government-owned facilities.

18 (7) A comprehensive, independent assessment
19 of emerging data center architectures and cooling
20 technologies is essential to inform efficient and cost-
21 effective deployment decisions across the Federal
22 Government.

23 **SEC. 3. LIQUID COOLING DEPLOYMENT AND SCALABILITY.**

24 (a) GAO REVIEW.—Not later than 30 days after the
25 date of the enactment of this Act, the Comptroller General

1 of the United States shall initiate a review of the research
2 and development needs, and the related market, techno-
3 logical, and regulatory conditions, affecting liquid cooling
4 utilization by data centers.

5 (b) ELEMENTS.—The review required under sub-
6 section (a) shall include the following:

7 (1) An evaluation of liquid cooling research and
8 development needs, and the costs and benefits for
9 high performance computing.

10 (2) A description of avoided costs of energy, in-
11 cluding deferred and avoided new electric trans-
12 mission and infrastructure upgrades and associated
13 costs.

14 (3) A description of increased compute capacity
15 by enabling more energy to be used for computing
16 workloads rather than cooling.

17 (4) A survey and analysis of existing research
18 on the positive and negative effects of liquid cooling
19 on computing performance, resiliency, and cyberse-
20 curity.

21 (5) An assessment of market trends and adop-
22 tion rates of liquid cooling in United States data
23 centers over the past five years.

24 (6) A comparison of direct-to-chip (DTC) liquid
25 cooling and immersion cooling approaches across

1 representative density bands, including relating to
2 thermal performance, maintainability, interoper-
3 ability, safety, failure modes, and lifecycle cost.

4 (7) An evaluation of coolant options, including
5 water, water-glycol, and engineered fluids, materials
6 compatibility, corrosion control, bio growth mitiga-
7 tion, filtration, deaeration, and fluid monitoring and
8 management.

9 (8) Recommendations relating to whether liquid
10 cooling should be considered as a primary cooling
11 option over air cooling due to the thermal conditions
12 of computing components in servers within data cen-
13 ters.

14 (9) Development of reference architectures and
15 layouts for rack, row, and room-level liquid distribu-
16 tion by density band and cooling approach.

17 (10) A survey of existing opportunities for
18 reusing waste heat produced by data centers.

19 (11) An evaluation of failure scenarios (such as
20 pump failures or fluid leaks) and mitigation strate-
21 gies, especially in shared co-location environments.

22 (c) REQUIREMENTS.—

23 (1) RECOMMENDATIONS.—In preparing the re-
24 view required under subsection (a), the Comptroller
25 General of the United States shall include rec-

ommendations, including considerations relating to the following:

(A) The Federal Government's utilization of and ongoing research on liquid cooling technologies.

(B) Best practices and industry standards for the design and operation of liquid cooling technologies.

(C) Methods to enhance the security, reliability, and resilience of computing equipment and data centers.

(D) Methods to accelerate education on operational best practices.

(2) STAKEHOLDER INPUT.—With the goal of identifying the best practices and industry standards referred to in paragraph (1)(A), the Comptroller General of the United States shall consult with stakeholders from Federal, State, and local governments, the private sector, academia, and National Laboratories.

(3) LIQUID COOLING ADVISORY ORGANIZATION.—

(A) IN GENERAL.—In furtherance of the review required under subsection (a), including the identification of best practices and industry

standards referred to in paragraph (1)(A), the Secretary of Energy and the Comptroller General of the United States shall jointly designate a liquid cooling industry organization with which to consult and coordinate in the preparation of such review.

(B) REQUIREMENTS.—The organization designated pursuant to subparagraph (A), whether preexisting or formed specifically for the purposes described in such subparagraph, shall satisfy the following criteria:

(i) Consist of interested parties who have expertise in liquid cooling system applications in the development, operation, and functionality of AI factories or data centers, information technology equipment, or software, as well as representatives of hardware manufacturers, data center operators, or AI factory development.

(ii) Consult with relevant stakeholders, including the Department of Energy, the National Laboratories, and any college, university, research institution, industry association, company, or public interest group with applicable expertise in

1 any of the subject matters areas specified
2 in clause (i).

3 (iii) Have as its mission the develop-
4 ment and promotion of liquid cooling for
5 data centers and information technology.

6 (d) REPORT.—Not later than 90 days after the date
7 of enactment of this Act, the Comptroller General of the
8 United States shall submit to the Secretary of Energy and
9 the appropriate congressional committees a written report
10 containing the results, findings, and any associated rec-
11 ommendations of the review required under subsection (a).

12 (e) DEPARTMENT OF ENERGY REVIEW.—Not later
13 than 180 days after receiving the report from the Comp-
14 troller General of the United States under subsection (d),
15 the Secretary of Energy shall—

16 (1) evaluate such report and any associated rec-
17 ommendations; and

18 (2) submit to the appropriate congressional
19 committees an assessment of such report and any
20 associated recommendations, including—

21 (A) relevant considerations for Congress
22 regarding the importance of liquid cooling for
23 the United States to maintain its global lead in
24 AI technologies; and

1 (B) recommendations for research and de-
2 velopment on liquid cooling and heat-reuse.

3 (f) DEFINITIONS.—In this section:

4 (1) AI.—The term “AI” has the meaning given
5 the term “artificial intelligence” in section 5002 of
6 the National Artificial Intelligence Initiative Act of
7 2020 (15 U.S.C. 9401).

8 (2) APPROPRIATE CONGRESSIONAL COMMIT-
9 TEES.—The term “appropriate congressional com-
10 mittees” means—

11 (A) the Committee on Energy and Natural
12 Resources of the Senate; and

13 (B) the Committee on Science, Space, and
14 Technology and the Committee on Energy and
15 Commerce of the House of Representatives.

16 (3) DIRECT-TO-CHIP (DTC) LIQUID COOLING.—
17 The term “direct-to-chip (DTC) liquid cooling”
18 means a liquid cooling method that involves circu-
19 lating a coolant in direct contact with applicable
20 heat-generating components, such as processors and
21 memory modules, to efficiently absorb and transfer
22 heat away.

23 (4) HEAT-REUSE.—The term “heat-reuse”
24 means the capture and transfer of waste heat from

1 liquid loops for beneficial secondary use through ap-
2 propriate interfaces and controls.

3 (5) IMMERSION COOLING.—The term “immer-
4 sion cooling” means a cooling technique that in-
5 volves submerging electronic components in a dielec-
6 tric fluid to absorb and dissipate heat within a pre-
7 set temperature range.

8 (6) LIQUID COOLING.—The term “liquid cool-
9 ing” means utilization of liquids to remove heat effi-
10 ciently from electronic components.

11 (7) NATIONAL LABORATORY.—The term “Na-
12 tional Laboratory” has the meaning given such term
13 in section 2 of the Energy Policy Act of 2005 (42
14 U.S.C. 15801).

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